

X400 SERVICE MANUAL

Sonim Technologies

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1.0 INTRODUCTION

1. PURPOSE

This manual provides the standardized operating instructions for X400 repairs.

2. REGULATORY INFORMATION

A. SECURITY

This wireless device, (the "Device") contains software owned by Sonim Technologies, Inc. ("Sonim") and its third party suppliers and licensors (collectively, the "Software"). As user of this Device, Sonim grants you a non-exclusive, non-transferable, non-assignable license to use the software & hardware solely in conjunction with the Device on which it is installed and/or delivered with. Nothing herein shall be construed as a sale of the Software & hardware to any third party.

You shall not reproduce, modify, distribute, reverse engineer, decompile, otherwise alter or use any other means to discover the source code of the Software, hardware or any component of the Software/hardware. For avoidance of doubt, you are at all times entitled to transfer all rights and obligations to the Software to a third party, solely together with the Device with which you received the Software, provided always that such third party agrees in writing to be bound by these rules. The validity, construction and performance of the license shall be governed by the laws of Delaware, United States & the manufacturer will not be responsible for any charges that result from unauthorized use.

B. PHONE CARE

Each Sonim phone has a designated IP class for dust and water protection, according to the IEC Ingress Protection (IP) Standard. This means that the phone is dust protected and can be submerged into 2 m deep water for up to 60 minutes. Immersion in deeper water can damage it and must be avoided.

Sonim phones are solid and built for heavy duty use. Its design protects against disassembly or mechanical damage when subjected to forces equal to free fall from the height of 2 meters. Subjecting the phone to stronger impact and forces can damage it and must be avoided.

C. MAINTAINENCE LIMITATIONS

Maintenance limitations on this model must be performed only by the manufacturer or its authorized agent. The user may not make any changes and/or repairs expect as specifically noted in this manual. Therefore, note that authorized alternations or repair may affect the regulatory status of the system and may void any remaining warranty.

D. ELECTROSTATIC SENSITIVE DEVICES

ATTENTION

Boards which contain Electrostatic Sensitive Devices (ESD) are indicated by the sign.

Following has to be taken while handling the ESD boards

- 1. Service personnel should ground themselves by using a wrist strap while working on the boards
- 2. When repairs are made to a system board, they should spread the floor with anti-static mat which is also grounded.
- 3. Use a suitable, grounded soldering iron.
- 4. Keep sensitive parts in protective packages until these are used.



2.0 REQUIREMENTS

REQUIREMENTS TO PERFORM THE ASSEMBLY & DISASSEMBLY OF HANDSETS

Sales pack or Spare parts of the handset.	
Tools	Tweezers, Phillips screwdriver, Heated platform, pry bar, Ejection Pin
ESD Gloves, shoes, Aprons, Wrist band	Antistatic Finger Sleeves
Clean sol or Isopropyl Alcohol [IPA]	
Hot air blower	
Soldering Iron	

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3.0 EXPLODED VIEW OF X400

	1	TP-LCD assembly	18	Rear camera lens
	2	LCD support	19	Flash lampshade
	3	foam Graphite sheet for front shell heat dissipation	20	Screen LCD Ground Sponge - Right
	4	LCD Grounding Sponge - Left	21	Battery double sided tape
	5	Front Camera Silicone Cover	22	BOX speaker waterproof foam adhesive
	6	Light Sensitive Silicone Case	23	Waterproof Silicone for Speakers
	7	Front Shell Assembly	24	Motor
	8	1012 Speaker	25	Antennae Small Board
	9	PTT Side Key	26	Small board assembly
	10	SIM card tray assembly	27	Main FPC
	11	PCBA motherboard	28	BOX speaker
	12	Rear main camera assembly	29	Battery
	13	Front Camera Assembly	30	Fastener
	14	Rear Auxiliary Camera Assembly	31	NFC antenna
	15	Backshell Antenna Bracket	32	Fingerprint Side Key
80 81 83 83 85 85 83 83 83 83 83 83 83 83 83 83 83 83 83	16	Battery cover waterproof foam adhesive	33	Rear Camera Silicone Cover
	17	Battery Cover	34	Volume Side Keys



4.0 HANDSET DISASSEMBLY

1. Place the device screen-side up on a 90-100 degree heating platform for 5-10 minutes, wait for the adhesive backing to soften and then use a pry bar to pry off the battery back cover from the four corners.(Pay attention to prevent deformation of the back cover)



2. Remove the battery back cover, lay the device flat with the screen facing down, and then use a Phillips screwdriver to remove the 9 motherboard back cover screws marked in the diagram.



3. Remove the back cover of the motherboard, first remove the battery FPC(1), and then carefully remove the USB(2), screen(3), power switch(4), front camera(5), and rear auxiliary camera(6) FPCs that are connected to the motherboard.Remove the front camera and rear auxiliary camera



NOTE:

Main vice board screws specifications: M1.4X3.0mm, cap diameter 2.5mm, cap height 0.8mm, cross machine teeth, black, rust resistance to fall

Shell material screw specifications: M1.4X4.5mm, cap diameter 2.5mm, cap height 0.8mm, cross machine teeth, black, rust-resistant and fall-resistant



4. Unscrew the motherboard fixing screws(1) with a Phillips-type screwdriver, carefully remove the 3 antenna connectors(2) and the audio amplifier connecting cable(3) with tweezers, and remove the card tray(4) with a card removal pin.



5. Use a pry bar to gently pry up the motherboard from the location shown in the figure, then carefully remove the motherboard.

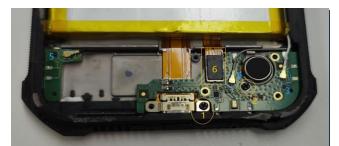


6. Use a Phillips screwdriver to unscrew the 7 screws shown in the illustration and remove the back cover.





7. Remove the screws(1,2), FPC(6), and antenna port connecting wires(3,4,5) shown in the figure, following the same procedure as before.



8.Disconnect the battery FPC and place the phone screen side down on a heating pad at 80 degrees for 3-5 minutes, then pry the battery out with a pry bar.





9.Disassembly is complete as shown.





NOTE: Prohibition of reuse of removed batteries!



5.0 MAT TEST OPERATING INSTRUCTIONS

MAT test is performed to test the functionality of mobile parameters. MAT test failure on particular parameter will allow you to decide which part needs to be replaced.

REQUIREMENTS:

- 1. Gloves
- 2. Distilled Water droplet bottle
- 3. Lint-free cloth
- 4. One Active SIM Card
- 5. Clean SD Card
- 6. Wi-Fi Access
- 7. NFC Tech Tiles
- 8. One Ejection Pin
- 9. OTG to Type-C Cable
- 10. Headset (Type-C)
- 11. Model-specific Phillips Screwdriver
- 12. Type-C Cable
- 13. Model-Specific Back Cover
- 14. Model-Specific Battery
- 15. 2nd Phone





Insert the two SIM cards and SD card into the device prior to MAT test to check and verify its functionality.

MANUAL AUTOMATION TEST [MAT] PROCEDURE:

Enter "*#7890#" on the phone dialer to get into Test mode. Select Device Test.

工厂测试	X400 📾	₩00\$	_ 🗆 X
Device Test	0P 0F 42L 42	R	► II :
	CAMERAREAR	COMPASS	CALIBRATION
ing Test	FLASHLIGHT	BACKLIGHT	TOUCHPANELE
, 105t	TP FREE	SINGLETOUCH	MULTITOUCH
eset	KEYPAD	LCM	VIBRATE
(coct	NFC	FINGERPRINT	SPEAKER
	SUBMIC	MAINMIC	RECEIVER
	HEADSET	CAMERABACK	CAMERAFRON
	PSENSOR	GSENSORCAL	GSENSOR
	MSENSOR	SYROSENSOR	GYROSCOPE
	LIGHTSENSOR	SDCARD	PRESSURE
	SARSENSORC	SAR SENSOR	BLUETOOTH
	WIFI	SIM1	SIM2
	GPS	USB	BATTERY
	CALL	OTG	HW INFO
t :	Click to enter	automatic test mo	ode

General Test:

1. Rear Auxiliary Camera - Select "Take Picture" and if an image is captured, return "PASS", otherwise click "Fail".

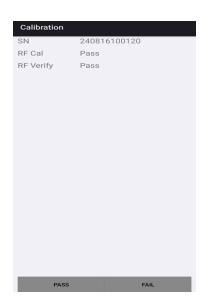




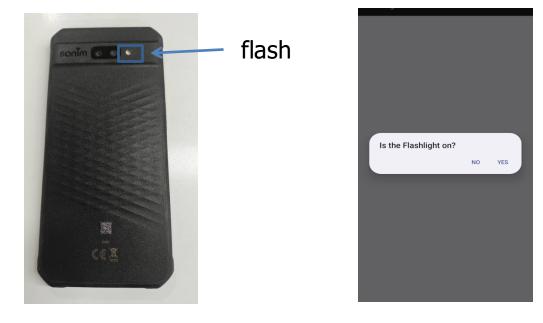
2. Compass - Check for proper compass function. If it's ok, then tap "PASS" or else tap "Fail".



3. Calibration check - The system automatically detects whether the test passes or not.



4. Flashlight - Check that the flash on the back of the phone is lit. If it's ok, then tap "PASS" or else tap "Fail".

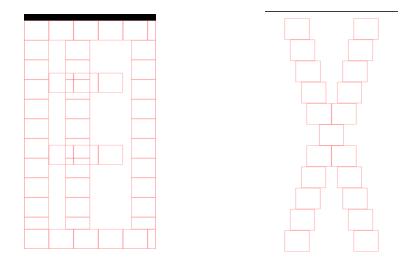




5. Backlight - Whether LCD screen is blinking. If it is blinking, then tap "PASS" or else tap "Fail"



6. Touch Panel Tes - Slide the pattern according to the track shown on the screen. If the TP function is normal, the device will return to the main menu.



7. TP-FREE TEST - Follow the prompts and slide the screen freely. If the TP function is normal, then tap "PASS" or else tap "Fail".





8. Single-touch Test - Click on the numbers or letters in sequence as required. If it's ok then tap "PASS" or else tap "Fail".



9. Multi-Touch Test - Multiple finger swipes on the screen. If it's ok, then tap "PASS" or else tap "Fail".

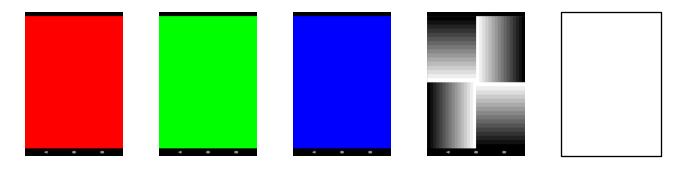


10. Keypad - Press each button on the device to check if their functions are ok, then tap "PASS" or else tap "Fail".

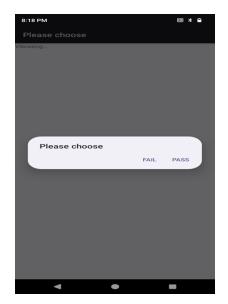
Keypad Please press the following k	evs
VOLUME_UP	
VOLUME_DOW	
POWER	
PROG	
FROG	
	FAIL



11. LCM TEST - Tap the screen to change the color sequentially, If it's ok then tap to choose "PASS" or else tap "Fail".



12. Vibrator Test - Check vibration is normal then tap "PASS" or else tap "Fail".



13. NFC - Try scanning with a NFC tag to check the NFC connectivity. If it's ok, then tap "PASS" or else tap "Fail".





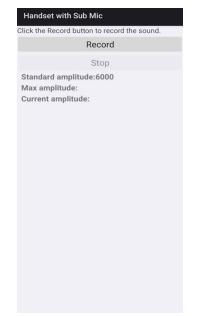
14. Fingerprint Test - Scan the finger on the sensor to check the fingerprint sensor. If it's ok, then tap "PASS" or else tap "Fail".



15. Speaker Test - Check if the sound is normal. If normal, click PASS, otherwise click Fail.

Speaker	
Playing	
Pass	Fail

16. SubMic Test - Say a sentence after clicking the "Record" button, then click "Stop". If it's ok, then tap "PASS" or else tap "Fail".

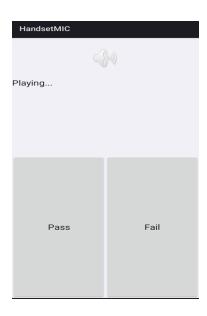




17. MainMic Test - Say a sentence after clicking the "Record" button, then click "Stop". If it's ok, then tap "PASS" or else tap "Fail".



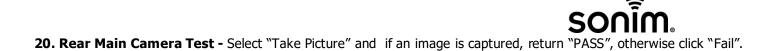
18. Receiver Test - Check if the sound is normal. If normal, click PASS, otherwise click Fail.



19.Headset Test -Insert the earphones and say a sentence after clicking the "Record" button, then click "Stop". If it's ok, then tap "PASS" or else tap "Fail".

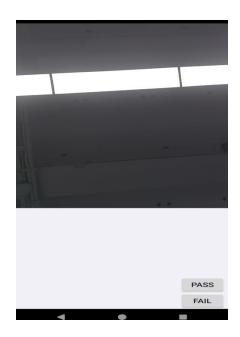
Headset When the recording can be heard Juring the testing process and he buttons are valid, the test is successful Click Record button to record sound.	P
Record Stop	
Please press the following keys END	
FAIL	





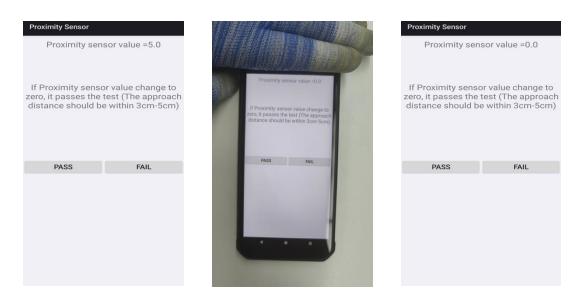


21. Front Camera Test - Select "Take Picture" and if an image is captured, return "PASS", otherwise click "Fail".

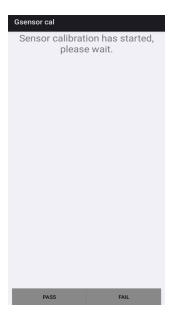




22. Proximity Sensor - Approach the sensor with your hand and click "PASS" if the test value is 0. .



23. Gravity Calibration - The system automatically detects whether the test passes or not.



24. Gravity Sensor - The mobile unit moves in all directions and can read X, Y and Z values. If normal, click "PASS", otherwise click "Fail".

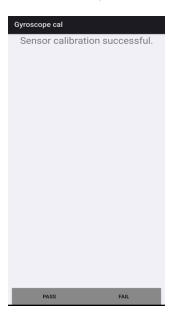
GSensorAssemble : (0.08978256	6, 8.028357, 4.84766)
X: PASS	
Y: PASS	
Z: PASS	
L. FA33	
D100	
PASS	FAIL



25. Magnetic Sensor - The system automatically detects whether the test passes or not. If normal, click "PASS".



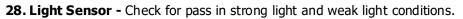
26. Gyroscope Calibration - The system automatically detects whether the test passes or not.

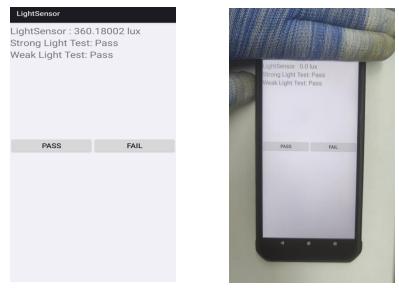


27. Gyroscope - It shows the X,Y & Z axis value when the phone moved in different direction. If it's ok, then tap "PASS" or else tap "Fail".

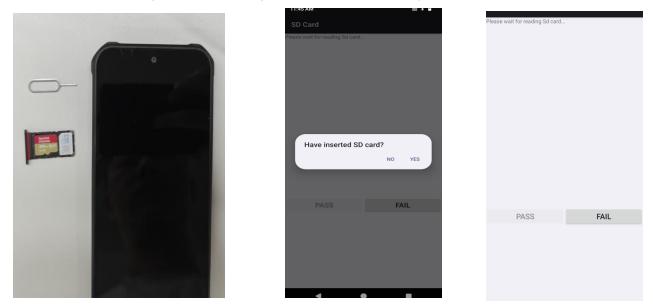
Gyroscope	
Gyroscope : (-0.19560903, 0.014	114743, 0.075101085)
PASS	FAIL







29. SD CARD Test - The system automatically detects whether the test passes or not.

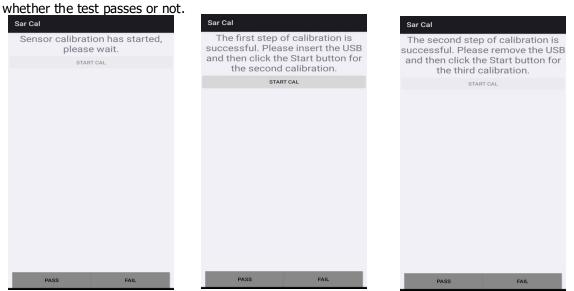


30. Pressure Test - The system automatically detects whether the test passes or not.





31. SAR Cal - Follow the system prompts to tap the screen and insert the USB, the system automatically detects



32. SAR Sensor - Follow the system prompts to gently press the designated spot on the side of the phone. If it's ok then tap "PASS" or else tap "Fail"._____



33. Bluetooth - Check the Bluetooth connectivity. If it's ok, then tap "PASS" or else tap "Fail".

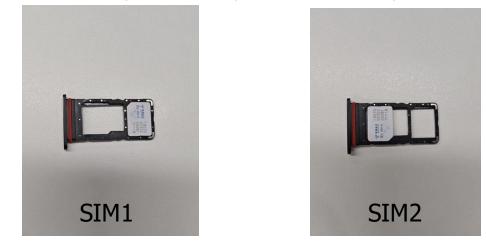
Bluetooth	
ADMIN-PC E8:B1:FC:5A:5D:DD	
null C2:09:0F:06:34:18	
null 66:15:E9:4A:8D:CC	
null 28:FF:B2:A6:A8:E4	
null 7D:D1:3C:12:0A:7E	
null 57:6F:4D:FF:B3:46	
Pass	Cancel



34. WIFI - Scan for WIFI connection. If it's ok, then tap "PASS" or else tap "Fail".

WiFi		
HWTEST002-5G	-62 dBm	5G
UNICAIR 8F Guest	-64 dBm	2.4G
UNICAIR 9F Guest	-42 dBm	2.4G
UNICAIR 9F 2.4G	-39 dBm	2.4G
HWTEST002-2.4G	-63 dBm	2.4G
GL-SFT1200-2.5G	-50 dBm	2.4G
UNICAIR 9F -5	0 dBm 5G	
GL-SFT1200-5G	-55 dBm	5G
ChinaNet-Jerr	-76 dBm 2.	4G
TP-LINK_2.4G_A935	-83 dBr	n 2.4G
UNICAIR 8F 2.4G	-71 dBm	2.4G
PASS		FAIL

35. SIM1&2 - The system automatically detects whether the test passes or not.

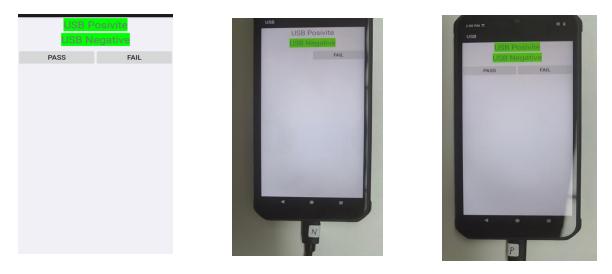


36. GPS Test - Check if the GPS location is shown accordingly. If it's ok, then tap "PASS" or else tap "Fail".

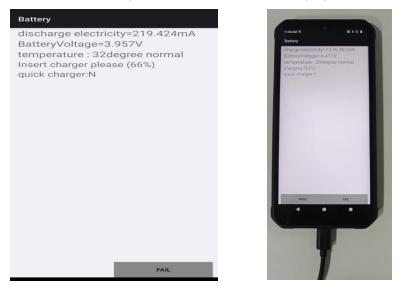
GPS	
Location unknown or lo	cating
●id 16 Snr:33.5	
● id 29 Snr:42.2	
● id 194 Snr:31.9	
● id 195 Snr:38.4	
● d 5 Snr:30.8	
PASS	FAIL



37. USB - Plug the USB forward and reverse into the device separately and check if it functions properly. If it's ok, then tap "PASS" or else tap "Fail".



38. Battery Test - Connect the charger to see if the status is charging. If it's ok, then tap "PASS" or else tap "Fail".



39. Call - machine dials out the call, and tests the quality of the call and check whether it is normal. If it's ok, then tap "PASS" or else tap "Fail".





40. OTG - Connect the phone using an OTG device. If it is normal, click "PASS", otherwise click "Fail".



41. Version - Check CSW, ISW version, IMEI, BT, WIFI. if normal, tap "PASS", otherwise tap "Fail".

Hardware Information		
Wifi MAC 00	/ifi MAC 00:24:A3:BF:FB:9D	
Bt MAC 00:24:A3:BF:FB:9C SN 240816100120 Cal status PASS IMEI 356133890006132		
3 sw version	56133890006140 X40.0-01-14.0-20.01.00	
Internal sw version	-2 n X40.0-01-14.0-20.01.00 -2-N-240910	
Hardware Version	X400_RevB-2	
PASS	FAIL	

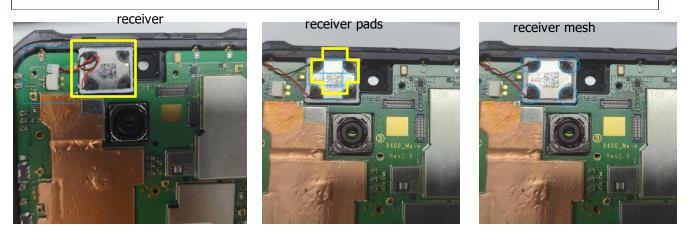
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6.0 TROUBLESHOOTING

6.1 RECEIVER PROBLEM

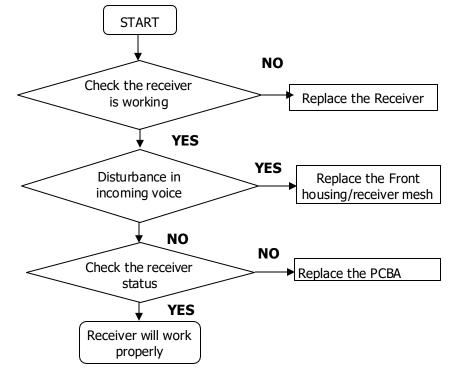
RECEIVER ASSEMBLY PART:

- a. Assemble the receiver to front housing in the right direction.
- b. Examine the receiver pin, replace the receiver if those pins are damaged or deformed.
- c. Replace the receiver mesh (dustproof) if it's damaged, as it provides dust & waterproof protection.
- **#** Clean the receiver pad and check the incoming voice.
- # Ensure the receiver mesh is not damaged before replacement as it results in incoming voice distortion.



OBSERVED PROBLEMS:-

- a. No/low incoming Voice
- b. Distortion in incoming voice.

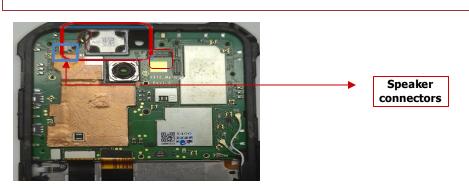


6.2 LOUD SPEAKER /RINGER/HF SPEAKER PROBLEM

RINGER ASSEMBLY PART:-

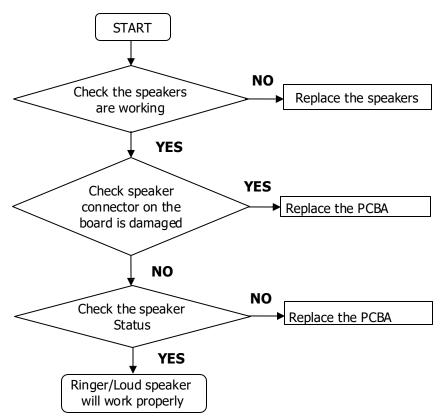
- a. The speakers fixed to front housing and connected to PCBA.
- b. Replace the speaker mesh if it's damaged as it's provided for dustproof protection.

Ensure the speaker holes are not blocked as it reduces the speaker volume.



OBSERVED PROBLEMS:-

- a. Loud speaker do not work or noise distortion in loud speaker voice.
- b. No ringing volume or noise or low ringing volume.

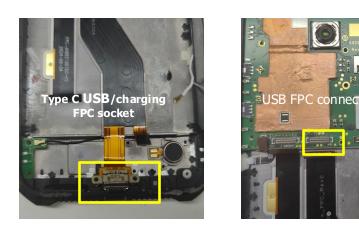




6.3 CHARGING PROBLEM

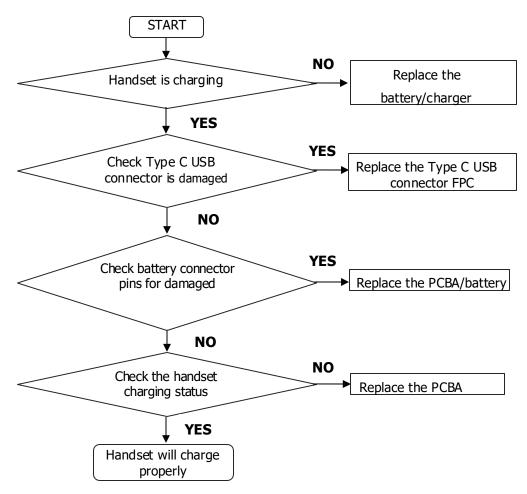
CHARGING SECTION ASSEMBLY PART:-

- a. Type C USB/charging connector is screwed to front housing that can be easily replaced, battery connector is soldered to the PCBA.
 - **#** Replace the Type C USB charging connector, if it is damaged.
 - # Replace the PCBA, if the USB connector on PCBA is damaged.



OBSERVED PROBLEMS:-

a. Handset not charging/charging intermittently.



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6.4 HEADSET OR EARPHONE PROBLEM

EARPHONE ASSEMBLY PART:-

- a. Secure Audio connector PCBA is assembled to FPC and connected to front housing.
- b. External accessory Requires a type-C connector wired headset.
- c. Ensure the FPC cable is assembled properly to PCBA pressing PIN connector.
- # Change the Secure Audio connector & FPC for headset related audio problems.



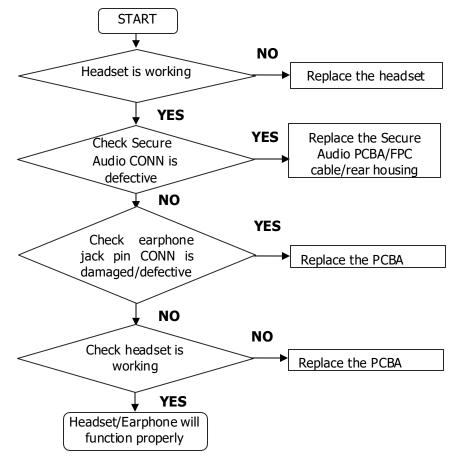


Headphone connector

Headphone FPC connector

OBSERVED PROBLEMS:-

- a. No/low Incoming & outgoing voice in Earphone
- b. Headset symbol shown without inserting the Headset.





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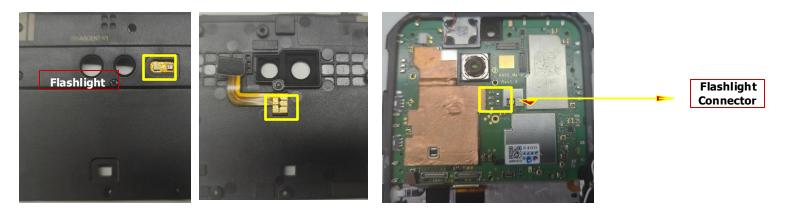
6.5 FLASHLIGHT

FLASHLIGHT ASSEMBLY PART:-

a. The flash and BAR sensor are mounted on the back cover of the motherboard and are connected to the PCBA through Pin connector.

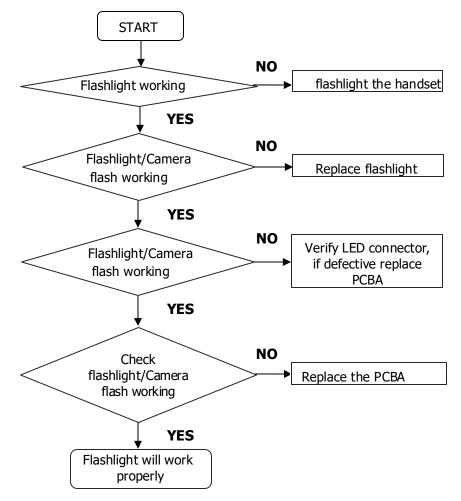
Replace the flashlight FPC for torch related problems. Check the FPC cable is assembled properly to PCBA pin connector. Replace the PCBA if still the issue persists.

Replace PCBA, if Pin connector is defective or any damages noticed on it.



OBSERVED PROBLEMS:-

- a. Flashlight not working
- b. Camera flash not working.





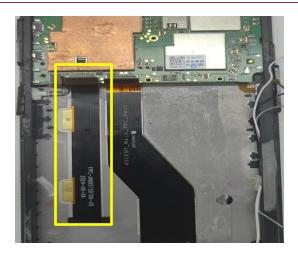
6.6 **DISPLAY PROBLEM**

LCD ASSEMBLY PART:-

a. LCD & touch screen are glued to front housing.

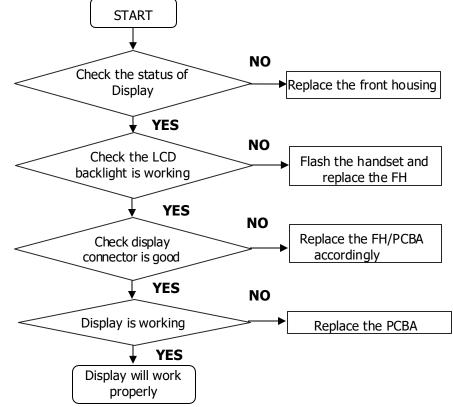
Replace the front housing if any dots or color patches are observed on the display as the LCD is glued to FH.
Flash the handset for DIM/Blur display/white display. If issue persists, replace the front housing/PCBA.
Replace the PCBA if the components around the display connector found missing or damaged.





OBSERVED PROBLEMS:-

- a. No or blur or dim or flickering display.
- b. Dots or colored patches on the display.

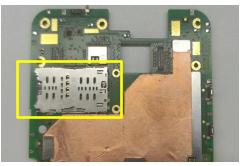


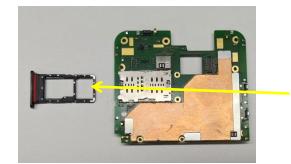
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6.7 SIM CARD PROBLEM

SIM CARD ASSEMBLY PART:-

a. X400 supports dual SIM cards. SIM Card connectors are soldered to PCBA.



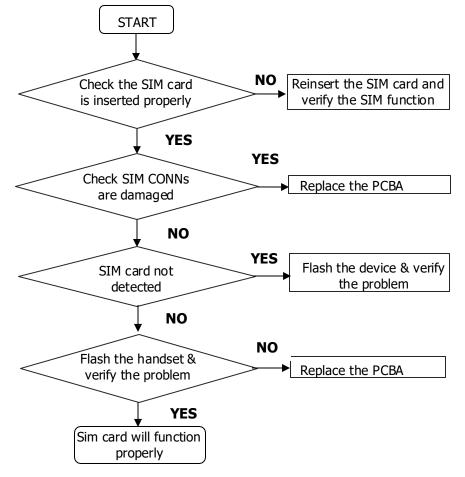


SIM&SD Card Tray

OBSERVED PROBLEMS:-

a. SIM card not detected or SIM errors.

NOTE: Insert the SIM card into the metal plate of the SIM card holder, and then close the card holder. TROUBLESHOOTING CHECKING FLOW:-

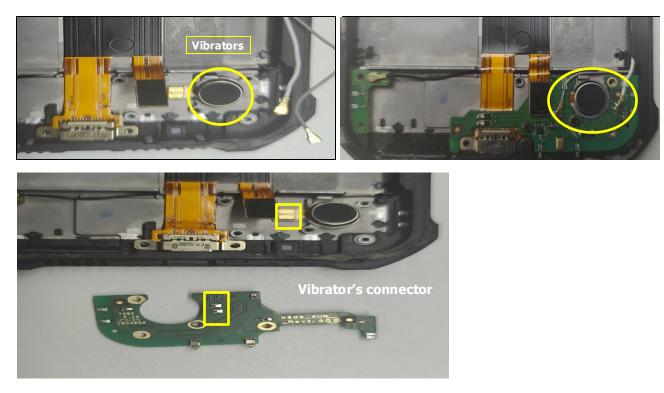


sonim

6.8 VIBRATOR PROBLEM

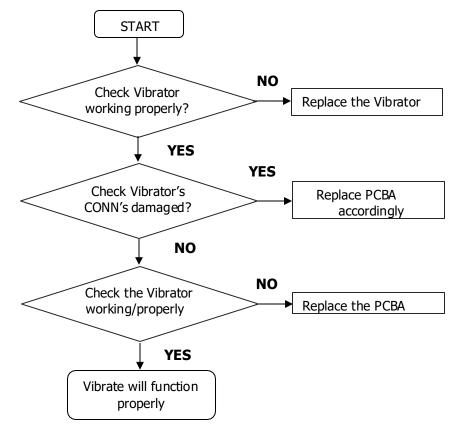
VIBRATOR ASSEMBLY PART:-

a. The X400 vibrator is assembled on the front housing.



OBSERVED PROBLEMS:-

a. Vibrator not working.



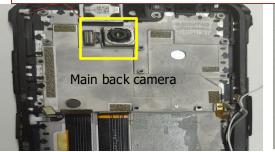


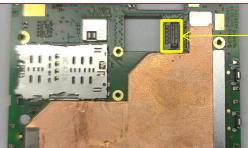
6.9 CAMERA PROBLEM

CAMERA ASSEMBLY PART:-

a. Rear main camera assembled on front case, rear secondary camera and front camera assembled on PCBA

Handsets resets when camera is switched ON, check the camera connector is damaged or camera is defective. Replace the camera and flash the handset. If still issue persists, replace the PCBA.





ightarrow Main back camera connector

Front Camera

Sub back camera



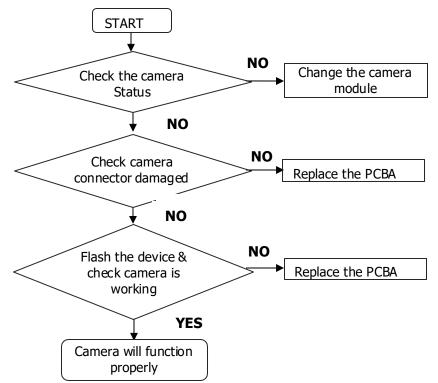


Front Camera connector

> Sub back camera connector

OBSERVED PROBLEMS:-

- a. Camera blur or poor picture/video quality.
- b. Handsets resets when camera is switched ON.
- c. Camera flash light not working/Camera not working.



6.10 MEMORY CARD PROBLEM

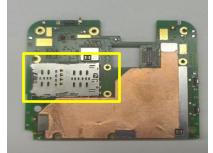


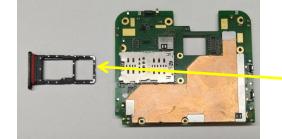
SD CARD ASSEMBLY PART:-

a. Memory Card connector is soldered to the PCBA.

Verify the defect with a good memory card, if it's working well then format the customer memory card.# If none of memory/storage issues is noticed then flash the handset and verify the problem.

Note: Insert the memory card into the metal plate of the SD card holder, and then close the card holder

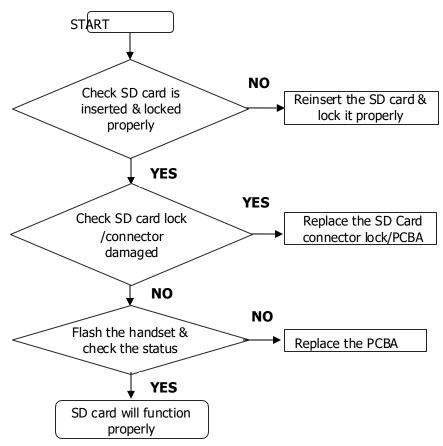




SIM&SD Card Tray

OBSERVED PROBLEMS:-

- a. Memory card could not detected.
- b. Memory card could not be reading/writing.

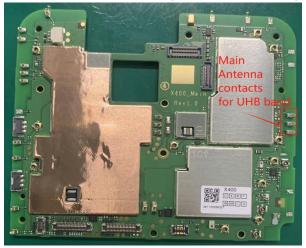


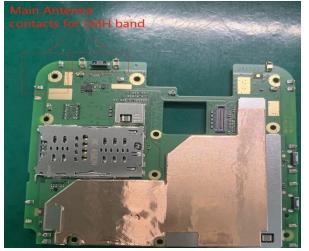


6.11 NETWORK PROBLEM

MAIN ANTENNA ASSEMBLY PART:-

a. Main antenna is fixed to PCBA through antenna contact pins & screw. Ensure the RF switch and main antenna pin contacts are not damaged before assembling the handset as it results in network issues.





DIVERSITY ANTENNA ASSEMBLY PART:-

X400 supports two diversity antennas. Two diversity antennas are implemented to improve the receiving ability of 4G LTE signals.

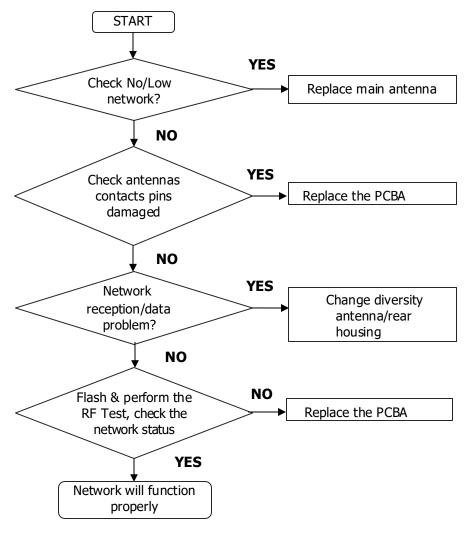


Flash the device and verify the problem for intermittent network problems, low signal strength & call drop issues. If issue persists replace the rear housing as the antennas are glued to it.

OBSERVED POBLEMS:-

- a. No Network
- b. Low signal strength
- c. Call drop
- d. Data downloading not happening/data downloading speed is low.

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6.12 MICROPHONE [MIC] PROBLEM

MIC ASSEMBLY PART:-

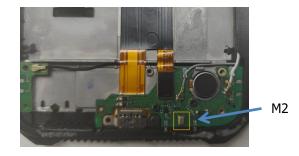
a. X400 supports two MICROPHONES M1(SUB), M2(MAIN).

b. Sub MIC on PCBA, Main MIC on a small board

Ensure the MIC holes and mesh not blocked in the front & rear housing as it results in outgoing voice problems like voice low, noise and echo problems.



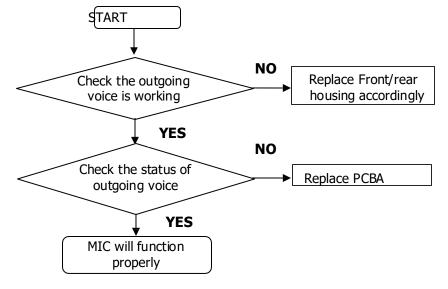






OBSERVED PROBLEMS:-

- a. No/Low outgoing voice.
- b. Distortion in outgoing voice.





7.0 HANDSET ASSEMBLY

1. Install the front, rear, and secondary cameras to the connectors on the board. Please note that the camera connector must be fully inserted during installation.



2. Install the motherboard into the front chassis, then use a Phillips screwdriver to screw in the motherboard fixing screws (1), use tweezers to install the 3 antenna connectors (2) and the audio amplifier connecting wires (3), and then install the bayonet (4). Pay attention to the mounting position and direction, and finally connect the FPC (5).



3.Install the small circuit board by screwing in the screws (1, 2), fixing the antenna (3, 4, 5), connecting the FPC (6), and finally locking the small circuit board bracket.







4. Remove release paper 1 and 2 from the front case, check and clean the battery compartment, insert the battery and secure the battery FPC as shown, then press the phone into the battery retainer and start the battery retainer up.





5. Place the motherboard back cover and lay the device flat with the screen facing down, then use a Phillips screwdriver to tighten the 9 motherboard back cover screws as shown in the figure.



6. Ensure that the 3 side buttons are correctly installed on the front case, peel off the battery cover adhesive sticker, snap on the battery cover in the direction shown in the figure, press the corners and place it into the battery cover press-fit retainer, and then turn on the power of the device to complete the assembly.

